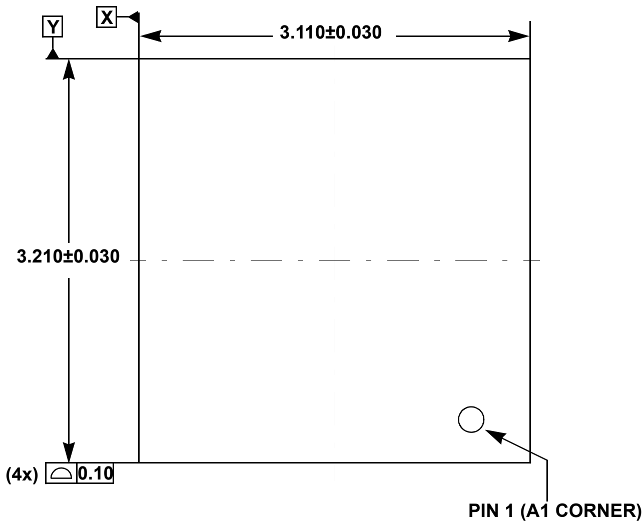
Package Outline Drawing

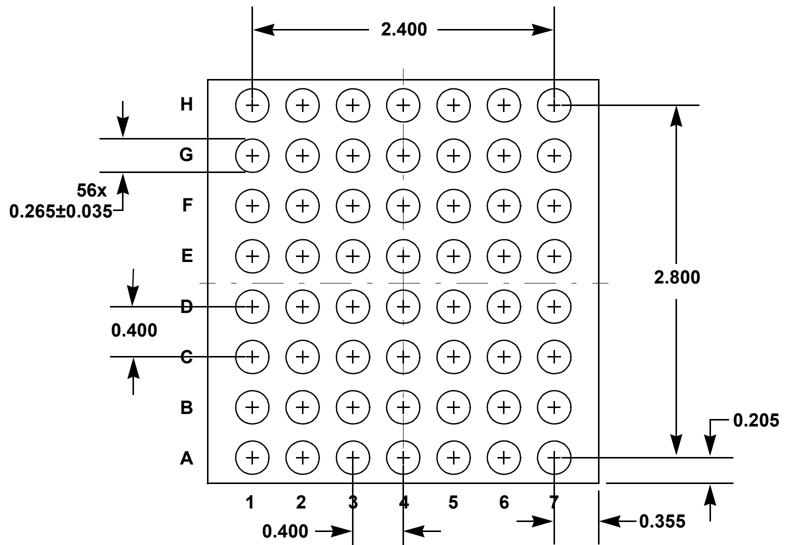
W7x8.56

56 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)

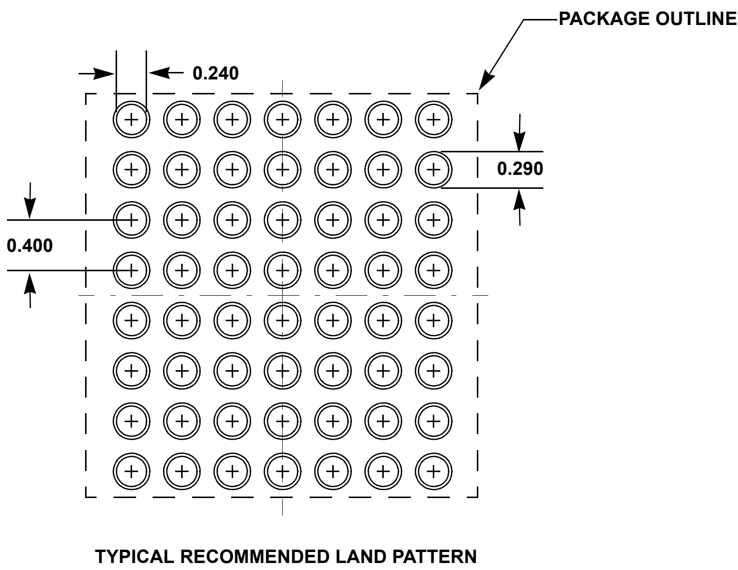
Rev 0, 7/13



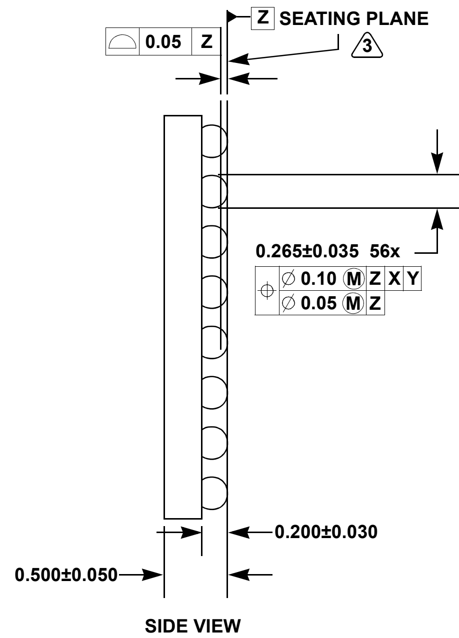
TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. Dimensions and tolerance per ASME Y 14.5M - 1994.
2. Dimension is measured at the maximum bump diameter parallel to primary datum Z
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. There shall be a minimum clearance of 0.10mm between the edge of the bump and the body edge.